

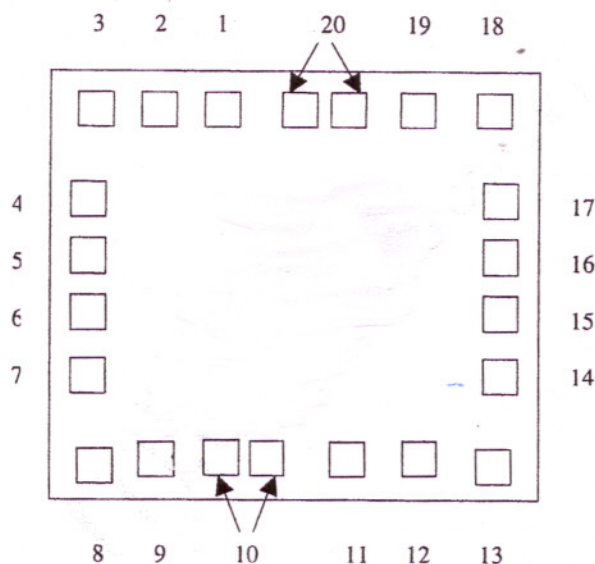


Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

PAD FUNCTIONS



- 1 N.1OE
- 2 1A0
- 3 2Y0
- 4 1A1
- 5 2Y2
- 6 1A2
- 7 2Y1
- 8 1A3
- 9 2Y0
- 10 GND (2 bond pads)
- 11 2A0
- 12 1Y3
- 13 2A1
- 14 1Y2
- 15 2A2
- 16 1Y1
- 17 2A3
- 18 1Y0
- 19 N.2OE
- 20 V_{CC} (2 bond pads)

The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Back potential is the electrical potential of the substrate (bulk silicon) which does not require an electrical connection unless stated in this drawing.

Note: 1 mil = 0.001inch

<u>APPROVED</u> GB DATE: 12/02/2010	<h2>54AC244</h2> <h3>TEXAS INSTRUMENTS</h3>	<u>DIE INFORMATION</u> DIMENSIONS (mils): 59 x 52 x 25 BOND PAD SIZE (mils): 3.76 x 3.76 min MIN PAD PITCH (mils): 5.57 MIN PITCH: BACK POTENTIAL: GND
<u>SERIAL NUMBER</u> M000086		<u>METALLISATION</u> TOP: Al BACK: Silicon Nitride